

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	1	"5460677".pn.	USPAT; EPO; JPO	OR	ON	2005/06/21 12:24
L2	1	"5364776".pn.	USPAT; EPO; JPO	OR	ON	2005/06/21 12:25
L3	1	"5364276".pn.	USPAT; EPO; JPO	OR	ON	2005/06/21 12:25
L5	54	higashida.in. and board.ti.	US-PGPUB; USPAT; EPO; JPO	OR	ON	2005/06/21 12:30
S1	47	(inject\$3 near2 (mould\$3 mold\$3) and (conductor wire pin post) same connect\$3 with (carrier interpos\$3)) and rough\$4 and (adhesive adher\$3)	USPAT; EPO; JPO	OR	ON	2004/10/15 11:48
S2	42	(mould\$3 mold\$3) same (conductor wire pin post) and connector with (carrier interposer) and rough\$4 and (adhesive adher\$3)	USPAT; EPO; JPO	OR	ON	2004/10/15 11:54
S3	2	(mould\$3 mold\$3) with resin same (conductor wire pin post) and connector and rough\$4 with (adhesive adher\$3) same bond\$3	USPAT; EPO; JPO	OR	ON	2004/10/15 12:12
S4	9	inject\$3 with (mould\$3 mold\$3) with resin same two near opening	USPAT; EPO; JPO	OR	ON	2004/10/15 12:15
S5	13	("2678592"   "2842955"   "2916233"   "2998216"   "3592437"   "3788581"   "3953029"   "4632346"   "4670208"   "4694190"   "4731915"   "4826127"   "4869456").PN.	USPAT	OR	ON	2004/10/15 12:14
S6	3	"5165651".URPN.	USPAT	OR	ON	2004/10/15 12:15
S7	313	inject\$3 with (mould\$3 mold\$3) with resin and two with (openings holes) with injection	USPAT; EPO; JPO	OR	ON	2004/10/15 12:17
S8	84	inject\$3 with (mould\$3 mold\$3) with resin and two with (openings holes) near3 injection	USPAT; EPO; JPO	OR	ON	2004/10/15 12:17
S9	24	inject\$3 with (mould\$3 mold\$3) with resin and two near3 (openings holes) near3 injection	USPAT; EPO; JPO	OR	ON	2004/10/15 12:28
S10	52	inject\$3 with (mould\$3 mold\$3) with resin and symmetric\$3 near3 (openings holes)	USPAT; EPO; JPO	OR	ON	2004/10/15 12:28
S11	1	("6265673").PN.	US-PGPUB; USPAT; USOCR	OR	OFF	2002/09/25 11:58
S12	1	"6265673".URPN.	USPAT	OR	ON	2002/09/25 11:35

S15 9	51	((mould\$3 mold\$3) with resin and (conductor wire pin post) with connect\$3 same mounting same (ic chip)) and circuit with (board substrate) and "29"/\$.ccls.	USPAT; EPO; JPO	OR	ON	2004/10/14 10:16
S16 0	131	((mould\$3 mold\$3) with resin and (conductor wire pin post) with connect\$3 same mounting same (ic chip)) and circuit with (board substrate) and (ic chip) near2 (carrier interpos\$3)	USPAT; EPO; JPO	OR	ON	2004/10/14 16:57
S16 1	126	((mould\$3 mold\$3) with resin and (conductor wire pin post) with connect\$3 same mounting same (ic chip)) and circuit with (board substrate) and (conductor wire pin post) with (carrier interpos\$3)	USPAT; EPO; JPO	OR	ON	2004/10/14 17:04
S16 2	12	inject\$3 near2: (mould\$3 mold\$3) with resin and (conductor wire pin post) with connect\$3 same mounting same (ic chip) and connector with (carrier interpos\$3)	USPAT; EPO; JPO	OR	ON	2004/10/14 17:06
S16 3	19	inject\$3 near2 (mould\$3 mold\$3) with resin and (conductor wire pin post) with connect\$3 same mounting and connector with (carrier interpos\$3)	USPAT; EPO; JPO	OR	ON	2004/10/14 17:08
S16 4	1151	inject\$3 near2 (mould\$3 mold\$3) and (conductor wire pin post) same connect\$3 with (carrier interpos\$3)	USPAT; EPO; JPO	OR	ON	2004/10/14 17:08
S16 5	82	(inject\$3 near2 (mould\$3 mold\$3) and (conductor wire pin post) same connect\$3 with (carrier interpos\$3)) and "264"/\$.ccls.	USPAT; EPO; JPO	OR	ON	2004/10/14 17:11
S16 6	105	(inject\$3 near2 (mould\$3 mold\$3) and (conductor wire pin post) same connect\$3 with (carrier interpos\$3)) and "361"/\$.ccls.	USPAT; EPO; JPO	OR	ON	2004/10/14 17:15
S16 7	82	(inject\$3 near2 (mould\$3 mold\$3) and (conductor wire pin post) same connect\$3 with (carrier interpos\$3)) and "174"/\$.ccls.	USPAT; EPO; JPO	OR	ON	2004/10/14 17:19
S16 8	13	("2948020"   "3576388"   "3985951"   "4379858"   "4423282"   "4443657"   "4450376"   "4647716"   "5286924"   "5441690"   "5455392"   "5519172"   "5562985").PN.	USPAT	OR	ON	2004/10/14 17:17
S16 9	1	"6054651".URPN.	USPAT	OR	ON	2004/10/14 17:18

S17 0	112	(inject\$3 near2 (mould\$3 mold\$3) and (conductor wire pin post) same connect\$3 with (carrier interpos\$3)) and "29"/\$.ccls.	USPAT; EPO; JPO	OR	ON	2004/10/14 17:25
S17 1	193	(inject\$3 near2 (mould\$3 mold\$3) and (conductor wire pin post) same connect\$3 with (carrier interpos\$3)) and "439"/\$.ccls.	USPAT; EPO; JPO	OR	ON	2004/10/14 18:06
S17 2	230	(inject\$3 near2 (mould\$3 mold\$3) and (conductor wire pin post) same connect\$3 with (carrier interpos\$3)) and "257"/\$.ccls.	USPAT; EPO; JPO	OR	ON	2004/10/14 18:12
S17 3	17	(inject\$3 near2 (mould\$3 mold\$3) and (conductor wire pin post) same connect\$3 with (carrier interpos\$3)) and "156"/\$.ccls.	USPAT; EPO; JPO	OR	ON	2004/10/14 18:13
S17 4	10	(inject\$3 near2 (mould\$3 mold\$3) and (conductor wire pin post) same connect\$3 with (carrier interpos\$3)) and "336"/\$.ccls.	USPAT; EPO; JPO	OR	ON	2004/10/15 11:42
S17 5	12	("2961746"   "3193789"   "3541222"   "3680037"   "3778900"   "3971610"   "4050756"   "4064623"   "4067945"   "4240198"   "4323593"   "4628406").PN.	USPAT	OR	ON	2004/10/14 18:29
S17 6	24	"5216807".URPN.	USPAT	OR	ON	2004/10/14 18:30
S17 7	5	"5618567".URPN.	USPAT	OR	ON	2004/10/14 18:31
S17 8	35	("2961746"   "3430338"   "3541222"   "3557446"   "3795037"   "3862790"   "3889363"   "3954317"   "4003621"   "4008300"   "4295700"   "4329780"   "4355199"   "4402562"   "4408814"   "4509099"   "4520562"   "4548451"   "4555523"   "4575166"   "4577918"   "4778950"   "4793814"   "4820170"   "4820376"   "4832609"   "4991290"   "4998885"   "5037312"   "5049084"   "5099309"   "5371654"   "5413489"   "5518410"   "5611696").PN.	USPAT	OR	ON	2004/10/14 18:32
S17 9	145	"3795037".URPN.	USPAT	OR	ON	2004/10/14 18:35
S18 0	78	"3862790".URPN.	USPAT	OR	ON	2004/10/14 18:40
S18 1	27	"3889363".URPN.	USPAT	OR	ON	2004/10/14 18:41